



Material Content Data Sheet



Sales Product Name		SAF-XE167FM-72F80L AA		Issued		25. September 2017		
MA#		MA001021916						
Package		PG-LQFP-144-13		Weight*		1459.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	38.601	2.65	2.65	26454	26454
leadframe	inorganic material	phosphorus	7723-14-0	0.122	0.01		84	
	non noble metal	zinc	7440-66-6	0.489	0.03		335	
	non noble metal	iron	7439-89-6	9.785	0.67		6706	
wire	non noble metal	copper	7440-50-8	397.309	27.23	27.94	272282	279407
	noble metal	gold	7440-57-5	3.925	0.27	0.27	2690	2690
	encapsulation	organic material	carbon black	1333-86-4	4.933	0.34		3381
encapsulation	plastics	epoxy resin	-	133.186	9.13		91274	
	inorganic material	silicondioxide	60676-86-0	848.443	58.15	67.62	581453	676108
leadfinish	non noble metal	tin	7440-31-5	9.120	0.62	0.62	6250	6250
plating	noble metal	silver	7440-22-4	3.110	0.21	0.21	2132	2132
glue	plastics	epoxy resin	-	2.539	0.17		1740	
	noble metal	silver	7440-22-4	7.616	0.52	0.69	5219	6959
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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